

CALL FOR ABSTRACTS



INTERNATIONAL THERMAL CONDUCTIVITY CONFERENCE (ITCC) & INTERNATIONAL THERMAL EXPANSION SYMPOSIUM (ITES) 2026

September 29 – October 1, 2026
Renaissance Columbus Westerville-Polaris Hotel
Columbus, OH

ceramics.org/itcc2026

THE CONFERENCES AT A GLANCE

The ITCC and the ITES are premier international meetings on the thermophysical properties of materials. They bring together researchers, engineers, and industry professionals from around the world to exchange knowledge on thermal conductivity, diffusivity, expansion, and related phenomena. First held in Columbus, OH, in 1961, these conferences have been hosted by distinguished institutions including Oak Ridge National Lab, Sandia National Lab, Ames Lab, NIST, Purdue University, Arizona State University, University of Michigan, and many others. In 2026, ITCC/ITES proudly return home to Columbus, co-hosted by the Edward Orton Jr. Ceramic Foundation & Hot Disk AB.

VENUE – RENAISSANCE COLUMBUS WESTERVILLE–POLARIS HOTEL

Ideally located near Polaris Parkway with easy access to restaurants, shopping, and downtown Columbus attractions.

THEMES & PRESENTATION OPPORTUNITIES

- Thermal conductivity & diffusivity
- Thermal expansion & thermo-mechanical stability
- Heat transfer, modeling & simulation
- Reference materials & standardization
- Steady-state & transient methods
- Thermorefectance & optical techniques
- High-performance materials
- Batteries & energy storage
- Thin films, adhesives & thermal interface materials
- Emerging thermal measurement technologies

STUDENT ENGAGEMENT & INCENTIVES

- Travel grants available
- Best poster awards
- Orton lab tour opportunity
- Resume/job board access
- Networking in a vibrant, collegial environment

PROGRAM HIGHLIGHTS

- Plenary & Invited Talks from leading experts
- Contributed Oral & Poster Sessions
- Table-top Exhibits showcasing the latest instruments and services
- Networking Opportunities including Welcome Reception, Poster Session, Conference Dinner

ORTON THERMAL MEASUREMENTS WORKSHOP

Tuesday, September 29, 2026

Full-day in-person workshop featuring expert-led lectures and live instrument demonstrations by Orton and Hot Disk AB. Participants will gain an exposure to advanced thermal measurement techniques including Dilatometry, Hot Disk, Hot Wire, Laser Flash, and DSC. Ideal for students, researchers, and professionals seeking to deepen their technical expertise in state-of-the-art measurement methods.

JOIN US IN 2026!

Don't miss this opportunity to attend or contribute to ITCC/ITES 2026 in Columbus, where the conference tradition returns home. Be part of the next chapter in the evolution of thermal science and property measurement.

Call for Abstracts deadline
is July 24, 2026

Hosted by:

The logo for Orton Hot Disk features the word "Orton" in a bold, white, sans-serif font, followed by "Hot Disk" in a similar font. A registered trademark symbol (®) is located to the right of "Hot Disk". A small red triangle is positioned above the letter "o" in "Orton".